I hereby certify that this correspondence is being electronically filed with the United States Patent and Trademark Office, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313 1450 on the below date.

y: Julia L

Date: November 2, 2006

Customer No.

026418

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.:

JG-SU-5224/500577.20073

U.S. Application No.:

10/562.235

Filing Date: December 22, 2005

International Application No.:

PCT/JP2005/006268

International Filing Date:

MARCH 31, 2005

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Priority Date Claimed:

APRIL 05, 2004

04 APRIL 2004

Title of Invention:

MANUFACTURING METHOD OF SEMICONDUCTOR WAFER AND SEMICONDUCTOR WAFER MANUFACTURED BY THIS METHOD

Applicant(s) for (DO/EO/US):

Syouji NOGAMI, Yukichi HORIOKA, and Shoichi YAMAUCHI

MAIL STOP MISSING PARTS Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

SUPPLEMENTAL RESPONSE TO NOTIFICATION OF MISSING REQUIREMENTS UNDER 35 U.S.C 371 IN THE UNITED STATES DESIGNATED/ELECTED OFFICE (DO/EO/US)

Sir:

Applicants submit herewith the following in order to complete the above application:

- (X) Executed Declaration and Power of Attorney.
- () Applicant is entitled to claim Small Entity Status [See 37 CFR 1.27].
- () Preliminary Amendment
- () Priority Document(s) No(s). _____, the priority(ies) of which is(are) claimed under 35 USC 119.
- (X) A copy of the Formalities Letter Confirmation No. 8539 dated September 20, 2006.
- () Authorization to charge Deposit Account No. 50-1529 in the amount of \$130.00

With the filing of these documents, it is submitted that the application is now complete and in form for examination. Accordingly, such examination and favorable action are earnestly solicited.

Respectfully submitted,

Dated: November 2, 2006

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